

PMP7033RevB_BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
2	C1 C4	330n	Capacitor, Film, 305VAC, 20±%	0.689 x 0.217 inch	B32922C3334K	Epcos
1	C10	1000u	Capacitor, Aluminum, 10V, ±20%	10x12mm	EEEFK1A102P	Panasonic
1	C11	470u	Capacitor, Aluminum, 10V, ±20%	8x10mm	EEEFK1A471P	Panasonic
1	C12	100n	Capacitor, Ceramic, 50V, X7R, 10%	1206	STD	STD
1	C13	100p	Capacitor, Ceramic, 500V, C0G, 10%	1206	STD	STD
1	C14	56uF	Capacitor, Aluminum Electrolytic, 35V	0.248 inch	STD	Rubycon
1	C15	6.8n	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
1	C16	1u	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
1	C17	100p	Capacitor, Ceramic, 50V, C0G, 10%	0603	STD	STD
1	C18	150p	Capacitor, Ceramic, 50V, C0G, 10%	0603	STD	STD
1	C19	1n	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	TDK
2	C2 C5	27u	Capacitor, Aluminum, 450V, 20%	14.5mm x 20mm	EKXJ451ELL270MJ20S	Nippon
1	C20	10n	Capacitor, Ceramic, 16V, X7R, 10%	0603	STD	STD
1	C21	DNP	Capacitor, Ceramic, 16V, X7R, 10%	0603	STD	STD
1	C22	DNP	Capacitor, Ceramic, 50V, C0G, 10%	0603	STD	STD
1	C23	22u	Capacitor, Aluminum Electrolytic, 35V	0.248 inch	STD	STD
1	C24	1n	Capacitor, Ceramic, 1000V, C0G, 10%	1206	STD	STD
1	C25	10n	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
1	C3	220pF	Capacitor, Ceramic, 500V, C0G, 10%	1206	STD	STD
2	C6-7	2n2	Capacitor, Ceramic, 2.5kVp, 300Vac, ± 10%	x	STD	STD
2	C8-9	47u	Capacitor, Ceramic, 10V, X5R, 10%	1812	C4532X5R1A476M	TDK
1	D10	BZX84C20	Diode, Zener, 20-V, 100-mA, 300-mW, 5%	SOT23	BZX84C20	Nippon
4	D1-4	US1M	Diode, Rectifier, 1A, 1000V	SMA	US1M	Diodes Inc
3	D5-6 D9	US1K-13	Diode, Rectifier, 1A, 800V	SMA	US1K-13	Diodes Inc
1	D7	B3100-13-F	Diode, Schottky, 3-A, 100-V	SMC	B3100-13-F	Vishay-Liteon
1	D8	RED	Diode, LED, Red, 2.1-V, 20-mA, 6-mcd	0603	LTST-C190CKT	Lite On
1	HS1	HS1	Heatsink, TO-220/218 vertical	0.640 x 0.640 inch	634-xxxAyy	Wakefield
1	J1	B2P3-VH	Header, Top Entry 2-pin, 312 mil spacing,	0.465 X 0.370 inch	B2P3-VH	EH
1	J2	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
1	L1	1mH	Inductor, Power, 0.2A	0.350 x 0.300 inch	744 772 102	WE
1	L2	5mH	Inductor, Coupled, 5mH ±30%	7.5x15 mm	744 821 150	WE
1	L3	2.2uH	Inductor, Power, 5A	0.350 x 0.300 inch	744 772 022	WE
1	Q1	MMBT2222A	TRANSISTOR, NPN, HIGH-PERFORMANCE, 500mA	SOT-23	MMBT2222A	Fairchild
1	Q2	STP3N150	MOSFET, Nch, 1500V, 1.6A, 6 Ohms	TO-220	STP3N150	ST
1	R1	47	Fusible Resistor, 5±%, 3W	1.300 X .210 inch	PWR4522A547R0JA	Bourns
1	R12	2	Resistor, Chip 1/4 watt, ±1%	1206	STD	STD
1	R14	1k	Resistor, Chip 1/4 watt, ±1%	1206	STD	STD
1	R15	DNP	Resistor, 1W, 2%	2512	STD	STD
1	R16	432k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R17	1k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R18	20	Resistor, Chip, 1/10W, 1%	0805	STD	STD
1	R19	80.6k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R2	2k1	Resistor, 1/4 watt, 5%	1206	STD	STD
1	R20	49.9	Resistor, Chip, 1/16W, 1%	0603	STD	STD
2	R21 R24	1.5k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R22	2.8	Resistor, Chip, 1/10W, 1%	0805	STD	STD
1	R23	4k99	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R25	47k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R26	1k24	Resistor, Chip, 1/16W, 1%	0603	STD	STD
2	R27 R30	DNP	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R29	27	Resistor, Chip, 1/10W, 1%	0805	STD	STD
1	R3	412k	Resistor, Metal Film, 1±%, 0.5-W,	1.300 X .210 inch	STD	STD
1	R4	S25K625E4R12	Varistor, 625V	0.335 x 0.551 inch	B72225S4621K101	Epcos
4	R5 R7 R9-10	680k	Resistor, 1/4 watt, 5%	1206	STD	STD
4	R6 R8 R11 R13	2MEG	Resistor, 1/4 watt, 5%	1206	STD	STD
4	SCR1-4		Through Hole for Screw #4 plated			
1	T1	2.3 mH	Transformer, ±10%	19x22 mm	063015-A	Kaschke
13	TP1-6 TP8-14	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	STD	Keystone
1	TP7	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	STD	Keystone
1	U1	UCC28600D	IC, Quasi-Resonant Flyback Green Mode Controller	SO8	UCC28600D	TI
1	U2	CNY17F-1M	IC, Optocoupler, 70 Vceo, Viso 5000Vrms, Wide Lead Space	DIP6 [400mil wide]	CNY17F-1M	Fairchild
1	U3	TLV431CDBZR	IC, Low-Voltage Adjustable Shunt Regulator	SOT23-3	TLV431CDBZx	TI
Notes:						
1. These assemblies are ESD sensitive, ESD precautions shall be observed.						
2. These assemblies must be clean and free from flux and all contaminants.						
Use of no clean flux is not acceptable.						
3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.						
4. Ref designators marked with an asterisk ("**") cannot be substituted.						
All other components can be substituted with equivalent MFG's components.						

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